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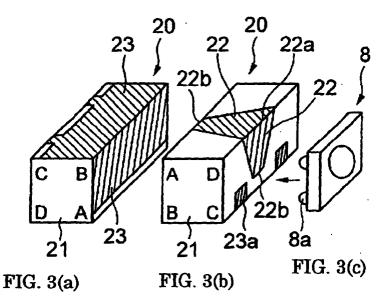
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(54) Electronic component-mounting substrate and electronic components

(57) The invention provides an electronic component-mounting substrate wherein joint reliability of microstrip lines at the line of intersection between two signal line surfaces is enhanced, and also an increase in signal reflection and a decrease in transmission due to a line impedance mismatching can be prevented. The width of a line junction 22a of microstrip lines 22 formed on two signal line surfaces of a rectangular-solid dielec-

tric 21 is provided to be broader than the width of a line end portion 22b. In addition, the width of the line junction 22a is designed such that the impedance would be equivalent to an impedance at a line end portion of the substituted lines if the microstrip lines 22 be equivalently substituted with lines on a substrate having a thickness equal to the length of a diagonal line of a cross section of the dielectric 21.





EUROPEAN SEARCH REPORT

Application Number EP 02 25 6069

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ANNEX TO THE EUROPEAN SEARCH REPORT ON EUROPEAN PATENT APPLICATION NO.

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